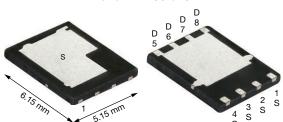


www.vishay.com

Vishay Siliconix

# N-Channel 40 V (D-S) MOSFET

# PowerPAK® SO-8DC



Top View

**Bottom View** 

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	40					
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 10 \text{ V}$	0.00088					
$R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = 4.5 \text{ V}$	0.00116					
Q <sub>g</sub> typ. (nC)	53					
I <sub>D</sub> (A) <sup>a, g</sup>	100					
Configuration	Single					

#### **FEATURES**

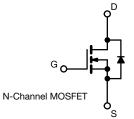
- TrenchFET® Gen IV power MOSFET
- Very low R<sub>DS</sub> Q<sub>g</sub> figure-of-merit (FOM)
- Tuned for the lowest R<sub>DS</sub> Q<sub>oss</sub> FOM
- Top side cooling feature provides additional venue for thermal transfer
- 100 % R<sub>q</sub> and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

#### **APPLICATIONS**

- · Synchronous rectification
- OR-ing
- High power density DC/DC
- · Motor drive control
- Battery management
- · Load switch







ORDERING INFORMATION	
Package	PowerPAK SO-8DC
Lead (Pb)-free and halogen-free	SiDR402DP-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V <sub>DS</sub>	40	V	
Gate-source voltage		V <sub>GS</sub>	+20, -16		
	T <sub>C</sub> = 25 °C		100 <sup>g</sup>		
Continuous drain surrent (T. 150 °C)	T <sub>C</sub> = 70 °C		100 <sup>g</sup>		
Continuous drain current (T <sub>J</sub> = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	64.6 <sup>b, c</sup>		
	T <sub>A</sub> = 70 °C		51.7 <sup>b, c</sup>	_	
Pulsed drain current (t = 100 μs)	I <sub>DM</sub>	400	A		
Continuous accuracy during disade accuracy.	T <sub>C</sub> = 25 °C		100 <sup>a</sup>		
Continuous source-drain diode current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	5.6 <sup>b, c</sup>		
Single pulse avalanche current	L = 0.1 mH	I <sub>AS</sub>	50		
Single pulse avalanche Energy	L = U. I MIN	E <sub>AS</sub>	125	mJ	
	T <sub>C</sub> = 25 °C		125		
Maximum navver dissination	T <sub>C</sub> = 70 °C		80	_ w	
Maximum power dissipation	T <sub>A</sub> = 25 °C	P <sub>D</sub>	6.25 <sup>b, c</sup>	VV	
	T <sub>A</sub> = 70 °C		4 b, c		
Operating junction and storage temperature range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +150		
Soldering recommendations (peak temperature) d, e		. 3	260	°C	

THERMAL RESISTANCE RATINGS							
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT		
Maximum junction-to-ambient b, f	t ≤ 10 s	R <sub>thJA</sub>	15	20			
Maximum junction-to-case (drain)	Steady state	$R_{thJC}$	0.8	1	°C/W		
Maximum junction-to-case (source)	Steady state	R <sub>thJC</sub>	1.1	1.4			

#### **Notes**

- a. Based on  $T_C$  = 25  $^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- t = 10 s
- See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8DC is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- Maximum under steady state conditions is 54 °C/W
- g. Package limited

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40	-	-	V	
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	1 050 A	-	24	-	>//00	
V <sub>GS(th)</sub> temperature coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA	-	-5.4	-	mV/°C	
Gate-source threshold voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.1	-	2.3	V	
Gate-source leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = +20, -16 \text{ V}$	-	-	± 100	nA	
7		V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V	-	-	1	μΑ	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C	-	-	10		
On-state drain current a	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	50	-	-	Α	
B :		$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}$	-	0.00073	0.00088		
Drain-source on-state resistance a	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A	-	0.00096	0.00116	Ω	
Forward transconductance a	g <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 20 A	-	147	-	S	
Dynamic <sup>b</sup>	<u> </u>				· · · · · · · · · · · · · · · · · · ·		
Input capacitance	C <sub>iss</sub>		-	9100	- 1		
Output capacitance	C <sub>oss</sub>		-	1650	-	рF	
Reverse transfer capacitance	C <sub>rss</sub>	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 0 V, f = 1 MHz		210	-		
C <sub>rss</sub> /C <sub>iss</sub> ratio			-	0.024	0.048		
		$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$	-	110	165		
Total gate charge	Qg		-	53	80		
Gate-source charge	Q <sub>qs</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$	-	22.5	-	nC	
Gate-drain charge	$Q_{gd}$			9.5	-	1	
Output charge	Q <sub>oss</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	-	75	-		
Gate resistance	$R_g$	f = 1 MHz	0.3	0.88	1.5	Ω	
Turn-on delay time	t <sub>d(on)</sub>		-	15	30		
Rise time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, R_{I} = 1 \Omega$	-	42	84		
Turn-off delay time	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	42	84	1	
Fall time	t <sub>f</sub>		-	10	20		
Turn-on delay time	t <sub>d(on)</sub>		-	45	90	ns	
Rise time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, R_1 = 1 \Omega$	-	100	200	-	
Turn-off delay time	t <sub>d(off)</sub>	$I_D \cong 20$ A, $V_{GEN} = 4.5$ V, $R_g = 1$ $\Omega$	-	56	112		
Fall time	t <sub>f</sub>	-		40	80		
Drain-Source Body Diode Characteristic	s		1				
Continuous source-drain diode current	Is	T <sub>C</sub> = 25 °C	-	-	100		
Pulse diode forward current (t <sub>p</sub> = 100 μs)	I <sub>SM</sub>		-	-	400	А	
Body diode voltage	V <sub>SD</sub>	I <sub>S</sub> = 10 A	-	0.73	1.1	V	
Body diode reverse recovery time	t <sub>rr</sub>		-	65	130	ns	
Body diode reverse recovery charge	Q <sub>rr</sub>	$I_F = 20 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	90	180	nC	
Reverse recovery fall time	t <sub>a</sub>	T <sub>J</sub> = 25 °C	-	37	-		
Reverse recovery rise time	t <sub>b</sub>			30	_	ns	

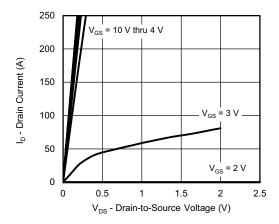
#### Notes

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

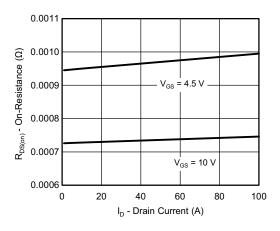
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



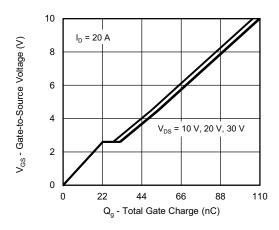
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



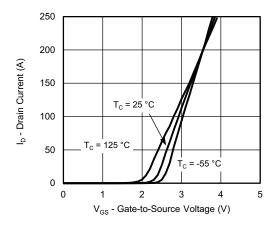
#### **Output Characteristics**



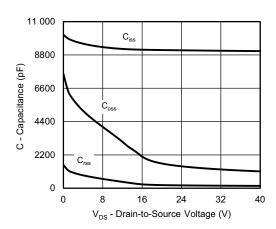
On-Resistance vs. Drain Current



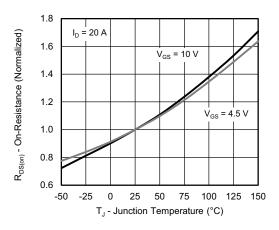
**Gate Charge** 



**Transfer Characteristics** 



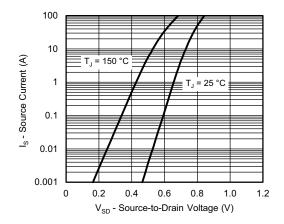
Capacitance



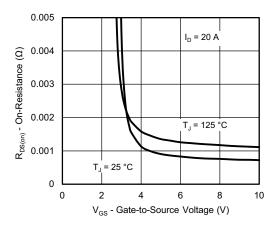
On-Resistance vs. Junction Temperature



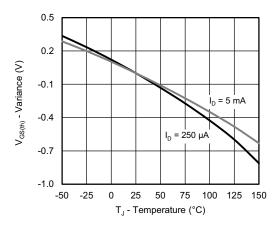
### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



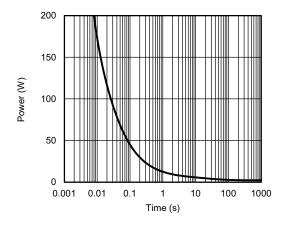
Source-Drain Diode Forward Voltage



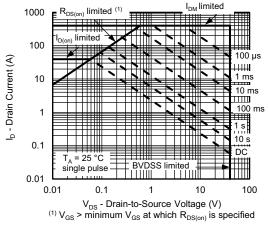
On-Resistance vs. Gate-to-Source Voltage



**Threshold Voltage** 



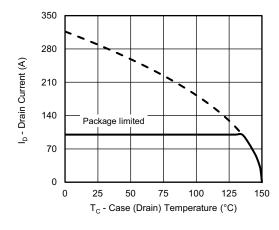
Single Pulse Power, Junction-to-Ambient



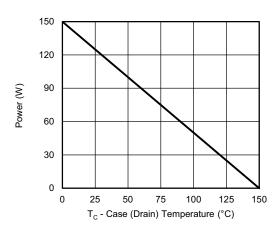
Safe Operating Area

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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating a



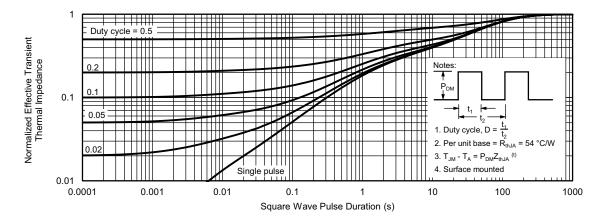
Power, Junction-to-Case

#### Note

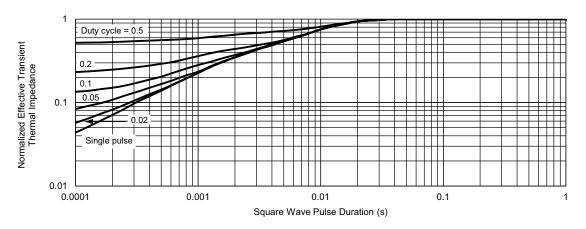
a. The power dissipation P<sub>D</sub> is based on T<sub>J</sub> (max.) = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



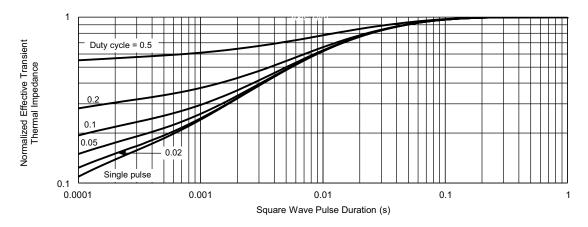
## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



#### Normalized Thermal Transient Impedance, Junction-to-Case (drain)

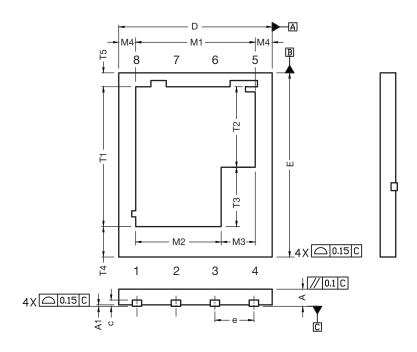


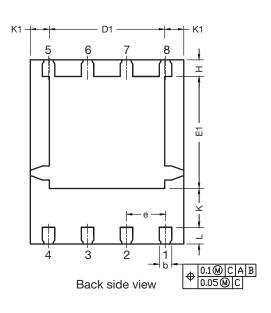
#### Normalized Thermal Transient Impedance, Junction-to-Case (source)

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg275606">www.vishay.com/ppg275606</a>.

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# PowerPAK® SO-8 Double Cooling Case Outline





DIM.	MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.51	0.56	0.61	0.012	0.014	0.016	
A1	0.00	0.02	0.05	0.000	0.0008	0.002	
b	0.36	0.41	0.46	0.014	0.016	0.018	
С	0.15	0.20	0.25	0.006	0.008	0.010	
D	4.90	5.00	5.10	0.193	0.197	0.201	
D1	3.71	3.76	3.81	0.146	0.148	0.150	
е		1.27 BSC			0.050 BSC		
Е	5.90	6.00	6.10	0.232	0.236	0.240	
E1	3.60	3.65	3.70	0.142	0.144	0.146	
Н	0.49	0.54	0.59	0.019	0.021	0.023	
K	1.22	1.27	1.32	0.048	0.050	0.052	
K1		0.64 typ.		0.025 typ.			
L	0.49	0.54	0.59	0.019	0.021	0.023	
M1	3.85	3.90	3.95	0.152	0.154	0.156	
M2	2.74	2.79	2.84	0.108	0.110	0.112	
M3	1.06	1.11	1.16	0.042	0.044	0.046	
M4		0.56 typ.		0.022 typ.			
N		8		8			
T1	4.51	4.56	4.61	0.178	0.180	0.182	
T2	2.58	2.63	2.68	0.102	0.104	0.106	
T3	1.88	1.93	1.98	0.074	0.076	0.078	
T4	0.97 typ.			0.038 typ.			
T5	0.48 typ.			0.019 typ.			

DWG: C040

DWG: 6048

Revison: 11-Jul-16

Document Number: 75846



# RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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